

## Reliability Results for Product Type BZX585-C5V1

Time period: Q4/2015 to Q3/2016

### Test Results

AEC-Q101 Test	Conditions	Duration	Quantity	Rejects
<b>TEST</b>				
# 1 Pre- and Post-Stress Electrical Test	$T_{amb} = 25\text{ °C}$	N/A	all parts	see below
# 2 <b>PC</b> Preconditioning	JESD22-A113 Bake $T_{amb} = 125\text{ °C}$ Soak $T_{amb} = 85\text{ °C}$ , RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	36160	0
# 5 <b>HTRB</b> High Temperature Reverse Bias	MIL-STD-750-1 M1038 Method A $T_j = T_{jmax}$ , $V_r = 100\%$ of max. datasheet reverse voltage	1000 hours	8388	0
# 7 <b>TC</b> Temperature Cycling	JESD22-A104 $-55\text{ °C}$ to $T_{jmax}$ , not to exceed $150\text{ °C}$	1000 cycles	9040	0
# 8 <b>AC</b> Autoclave	JESD22-A102 $T_{amb} = 121\text{ °C}$ , RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	9040	0
# 9 <b>H3TRB</b> High Humidity High Temperature Reverse Bias	JESD22-A101 $T_{amb} = 85\text{ °C}$ , RH = 85%, $V_R > 80\%$ of rated reverse voltage	1000 hours	9040	0
# 10 <b>IOL</b> Intermittent Operating Life	MIL-STD-750 Method 1037 $t_{on} = t_{off}$ , devices powered to insure $\Delta T_j = 125\text{ °C}$ for 7500 cycles or $\Delta T_j = 100\text{ °C}$ for 15000 cycles	1000 hours	9040	0
# 20 <b>RSH</b> Resistance to Solder Heat	JESD22-A111 $260\text{ °C} \pm 5\text{ °C}$	10 s	2250	0
# 21 <b>SD</b> Solderability	J-STD-002 Test method B and D		1950	0

### Calculation of FIT and MTBF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, AEC-Q101 Test # 5)  
Confidence level 60%, derated to  $55\text{ °C}$ , activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate	MTBF
Nexperia DHAM	Small Signal Bipolar	8388	0	0.51 FIT	225327 years